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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2852  
Examiner: To be assigned

In Re PATENT APPLICATION Of:



Applicants : Mitsuhiro OGIHARA et al. )  
Serial No. : 10/734,676 )  
Filed : December 15, 2003 )  
For : SEMICONDUCTOR APPARATUS )  
HAVING ADHESION LAYER )  
AND SEMICONDUCTOR THIN )  
FILM )

**REQUEST FOR  
CORRECTED  
FILING RECEIPT**

Attorney Ref: MAE 304

Commissioner for Patents  
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Please correct the Official Filing Receipt in the above-captioned matter as follows:

-The Filing Fee Rec'd should be "860" instead of "842".

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Respectfully submitted,

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Date: July 8, 2004

RHB:dt

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- Copy of Official Filing Receipt with Corrections Marked in Red

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/734,676	12/15/2003	2852	842 <u>860</u>	MAE 304	24	24	1

CONFIRMATION NO. 6298

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## FILING RECEIPT



\*OC000000012242966\*

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## Applicant(s)

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## Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 2002-373882 12/25/2002

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Early Publication Request: No

## Title

Semiconductor apparatus having adhesion layer and semiconductor thin film